. .reescale Semiconductor
Technical Data

Document Number: MD7IC2250N
Rev. 0, 12/2010

RF LDMOS Wideband Integrated Power Amplifiers

The MD7IC2250N wideband integrated circuit is designed with on-chip matching that makes it usable from 2000 to 2200 MHz. This multi-stage structure is rated for 24 to 32 Volt operation and covers all typical cellular base station modulation formats.

- Typical Single-Carrier W-CDMA Performance: V_{DD} = 28 Volts, $I_{DQ1(A+B)}$ = 80 mA, $I_{DQ2(A+B)}$ = 520 mA, P_{out} = 5.3 Watts Avg., IQ Magnitude Clipping, Channel Bandwidth = 3.84 MHz, Input Signal PAR = 7.5 dB @ 0.01% Probability on CCDF.

Frequency	G_{ps} (dB)	PAE (%)	ACPR (dBc)
2110 MHz	31.2	17.0	-48.3
2140 MHz	31.1	16.8	-49.3
2170 MHz	31.1	16.8	-50.1

- Capable of Handling 10:1 VSWR, @ 32 Vdc, 2140 MHz, 63 Watts CW Output Power (3 dB Input Overdrive from Rated P_{out})
- Typical P_{out} @ 1 dB Compression Point ≃ 54 Watts CW

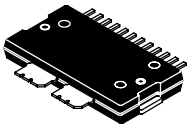
Features

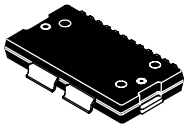
- Characterized with Series Equivalent Large-Signal Impedance Parameters and Common Source S-Parameters
- On-Chip Matching (50 Ohm Input, DC Blocked)
- Integrated Quiescent Current Temperature Compensation with Enable/Disable Function [1]
- Integrated ESD Protection
- Designed for Digital Predistortion Error Correction Systems
- Optimized for Doherty Applications
- 225°C Capable Plastic Package
- RoHS Compliant
- In Tape and Reel. R1 Suffix = 500 Units, 44 mm Tape Width, 13 inch Reel.

MD7IC2250NR1
MD7IC2250GNR1
MD7IC2250NBR1

2110-2170 MHz, 5.3 W AVG., 28 V SINGLE W-CDMA RF LDMOS WIDEBAND INTEGRATED POWER AMPLIFIERS

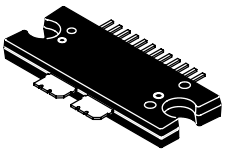
CASE 1618-02
TO-270 WB-14
PLASTIC
MD7IC2250NR1





CASE 1621-02
TO-270 WB-14 GULL
PLASTIC
MD7IC2250GNR1

CASE 1617-02
TO-272 WB-14
PLASTIC
MD7IC2250NBR1



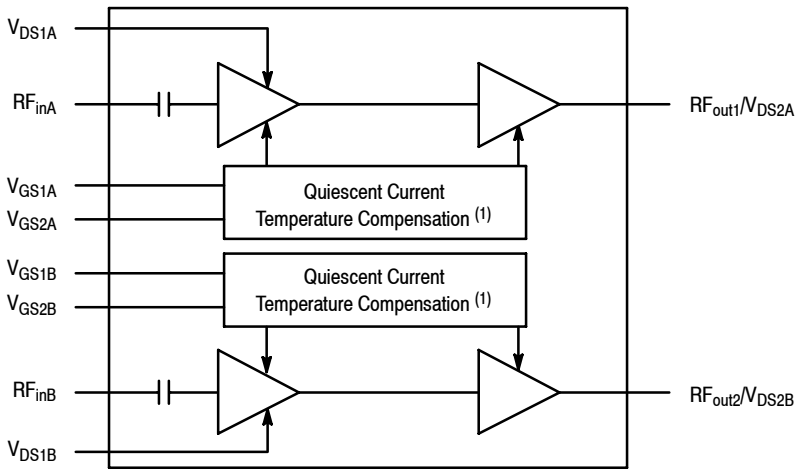
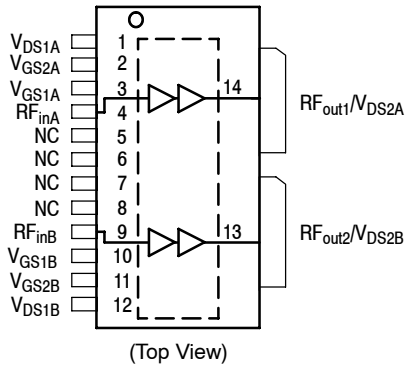


Figure 1. Functional Block Diagram



Note: Exposed backside of the package is the source terminal for the transistors.

Figure 2. Pin Connections

1. Refer to AN1977, *Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family* and to AN1987, *Quiescent Current Control for the RF Integrated Circuit Device Family.* Go to http://www.freescale.com/rf. Select Documentation/Application Notes - AN1977 or AN1987.

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Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +65	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +10	Vdc
Operating Voltage	V_{DD}	32, +0	Vdc
Storage Temperature Range	T_{stg}	- 65 to +150	°C
Case Operating Temperature	T_C	150	°C
Operating Junction Temperature (1,2)	T_J	225	°C
Input Power	P_{in}	28	dBm

Table 2. Thermal Characteristics

Characteristic	Symbol	Value (2,3)	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$		°C/W
Case Temperature 74°C, 5.3 W CW, 2170 MHz			
Stage 1, 28 Vdc, $I_{DQ1(A+B)}$ = 80 mA		5.3	
Stage 2, 28 Vdc, $I_{DQ2(A+B)}$ = 520 mA		1.1	
Case Temperature 80°C, 50 W CW, 2170 MHz			
Stage 1, 28 Vdc, $I_{DQ1(A+B)}$ = 80 mA		5.0	
Stage 2, 28 Vdc, $I_{DQ2(A+B)}$ = 520 mA		0.95	

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22-A114)	1A (Minimum)
Machine Model (per EIA/JESD22-A115)	A (Minimum)
Charge Device Model (per JESD22-C101)	II (Minimum)

Table 4. Moisture Sensitivity Level

Test Methodology	Rating	Package Peak Temperature	Unit
Per JESD22-A113, IPC/JEDEC J-STD-020	3	260	°C

Table 5. Electrical Characteristics (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Stage 1 - Off Characteristics (4)					
Zero Gate Voltage Drain Leakage Current (V_{DS} = 65 Vdc, V_{GS} = 0 Vdc)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current (V_{DS} = 28 Vdc, V_{GS} = 0 Vdc)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current (V_{GS} = 1.5 Vdc, V_{DS} = 0 Vdc)	I_{GSS}	—	—	1	μAdc
Stage 1 - On Characteristics					
Gate Threshold Voltage (4) (V_{DS} = 10 Vdc, I_D = 23 μAdc)	$V_{GS(th)}$	1.2	2.0	2.7	Vdc
Gate Quiescent Voltage (V_{DS} = 28 Vdc, $I_{DQ1(A+B)}$ = 80 mA)	$V_{GS(Q)}$	—	2.7	—	Vdc
Fixture Gate Quiescent Voltage (V_{DD} = 28 Vdc, $I_{DQ1(A+B)}$ = 80 mA, Measured in Functional Test)	$V_{GG(Q)}$	6.0	7.0	8.0	Vdc

1. Continuous use at maximum temperature will affect MTTF.
2. MTTF calculator available at http://www.freescale.com/rf. Select Software & Tools/Development Tools/Calculators to access MTTF calculators by product.
3. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers.* Go to http://www.freescale.com/rf. Select Documentation/Application Notes - AN1955.
4. Each side of device measured separately.

(continued)

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Table 5. Electrical Characteristics (T_A = 25°C unless otherwise noted) **(continued)**

Characteristic	Symbol	Min	Typ	Max	Unit
Stage 2 - Off Characteristics [1]					
Zero Gate Voltage Drain Leakage Current (V_{DS} = 65 Vdc, V_{GS} = 0 Vdc)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current (V_{DS} = 28 Vdc, V_{GS} = 0 Vdc)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current (V_{GS} = 1.5 Vdc, V_{DS} = 0 Vdc)	I_{GSS}	—	—	1	μAdc
Stage 2 - On Characteristics					
Gate Threshold Voltage [1] (V_{DS} = 10 Vdc, I_D = 150 μAdc)	$V_{GS(th)}$	1.2	2.0	2.7	Vdc
Gate Quiescent Voltage (V_{DS} = 28 Vdc, $I_{DQ2(A+B)}$ = 520 mA)	$V_{GS(Q)}$	—	2.7	—	Vdc
Fixture Gate Quiescent Voltage (V_{DD} = 28 Vdc, $I_{DQ2(A+B)}$ = 520 mA, Measured in Functional Test)	$V_{GG(Q)}$	5.5	6.3	7.5	Vdc
Drain-Source On-Voltage [1] (V_{GS} = 10 Vdc, I_D = 1 Adc)	$V_{DS(on)}$	0.1	0.24	1.2	Vdc
Functional Tests [2,3] (In Freescale Wideband 2110-2170 Test Fixture, 50 ohm system) V_{DD} = 28 Vdc, $I_{DQ1(A+B)}$ = 80 mA, $I_{DQ2(A+B)}$ = 520 mA, P_{out} = 5.3 W Avg., f = 2170 MHz, Single-Carrier W-CDMA, IQ Magnitude Clipping, Input Signal PAR = 7.5 dB @ 0.01% Probability on CCDF. ACPR measured in 3.84 MHz Channel Bandwidth @ ±5 MHz Offset.					
Power Gain	G_{ps}	30.0	31.1	34.0	dB
Power Added Efficiency	PAE	15.0	16.8	—	%
Adjacent Channel Power Ratio	ACPR	—	-50.1	-47.0	dBc
Input Return Loss	IRL	—	-14	-9	dB

Typical Broadband Performance (In Freescale Test Fixture, 50 ohm system) V_{DD} = 28 Vdc, $I_{DQ1(A+B)}$ = 80 mA, $I_{DQ2(A+B)}$ = 520 mA, P_{out} = 5.3 W Avg., Single-Carrier W-CDMA, IQ Magnitude Clipping, Input Signal PAR = 7.5 dB @ 0.01% Probability on CCDF. ACPR measured in 3.84 MHz Channel Bandwidth @ ±5 MHz Offset.

Frequency	G_{ps} (dB)	PAE (%)	ACPR (dBc)	IRL (dB)
2110 MHz	31.2	17.0	-48.3	-9
2140 MHz	31.1	16.8	-49.3	-11
2170 MHz	31.1	16.8	-50.1	-14

1. Each side of device measured separately.
2. Part internally matched both on input and output.
3. Measurement made with device in straight lead configuration before any lead forming operation is applied.

(continued)

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Table 5. Electrical Characteristics (T_A = 25°C unless otherwise noted) **(continued)**

Characteristic	Symbol	Min	Typ	Max	Unit
Typical Performance (In Freescale Test Fixture, 50 ohm system) V_{DD} = 28 Vdc, $I_{DQ1(A+B)}$ = 80 mA, $I_{DQ2(A+B)}$ = 520 mA, 2110–2170 MHz Bandwidth					
P_{out} @ 1 dB Compression Point, CW	P1dB	—	54	—	W
IMD Symmetry @ 50 W PEP, P_{out} where IMD Third Order Intermodulation ≅ 30 dBc (Delta IMD Third Order Intermodulation between Upper and Lower Sidebands > 2 dB)	IMD_{sym}	—	16	—	MHz
VBW Resonance Point (IMD Third Order Intermodulation Inflection Point)	VBW_{res}	—	70	—	MHz
Quiescent Current Accuracy over Temperature [1,2] with 4.7 kΩ Gate Feed Resistors (–30 to 85°C) Stage 1 Stage 2	ΔI_{QT}	— —	1.5 5.0	— —	%
Gain Flatness in 60 MHz Bandwidth @ P_{out} = 5.3 W Avg.	G_F	—	0.1	—	dB
Gain Variation over Temperature (–30°C to +85°C)	ΔG	—	0.028	—	dB/°C
Output Power Variation over Temperature (–30°C to +85°C)	ΔP1dB	—	0.028	—	dB/°C

1. Each side of device measured separately.
2. Refer to AN1977, *Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family* and to AN1987, *Quiescent Current Control for the RF Integrated Circuit Device Family*. Go to http://www.freescale.com/rf.Select Documentation/Application Notes – AN1977 or AN1987.

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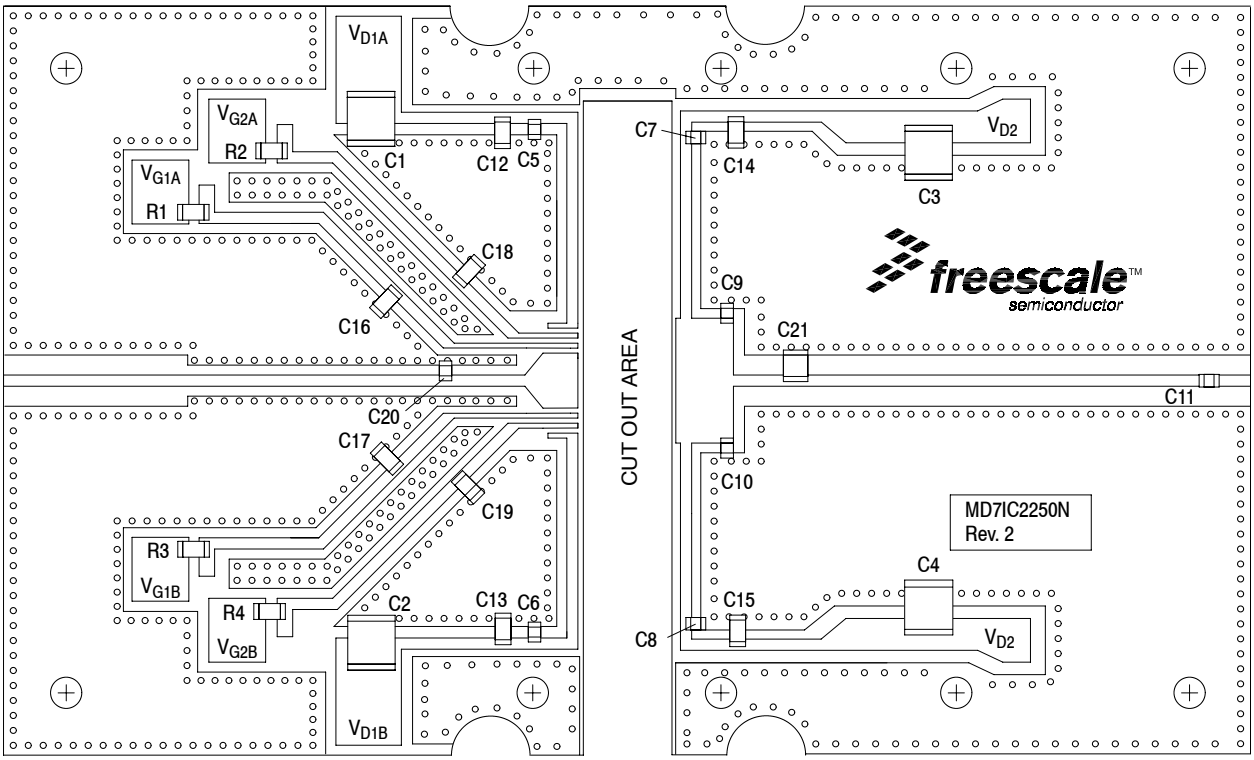

Figure 3. MD7IC2250NR1(GNR1)(NBR1) Test Circuit Component Layout

Table 6. MD7IC2250NR1(GNR1)(NBR1) Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
C1, C2, C3, C4	10 μF Chip Capacitors	GRM55DR61H106KA88L	Murata
C5, C6, C7, C8	5.6 pF Chip Capacitors	ATC600F5R6BT250XT	ATC
C9, C10	2.0 pF Chip Capacitors	ATC600F2R0BT250XT	ATC
C11	33 pF Chip Capacitor	ATC600F330JT250XT	ATC
C12, C13	1.0 μF Chip Capacitors	GRM31MR71H105KA88L	Murata
C14, C15, C16, C17, C18, C19	4.7 μF Chip Capacitors	GRM31CR71H475KA12L	Murata
C20	1.8 pF Chip Capacitor	ATC600F1R8BT250XT	ATC
C21	1.5 pF Chip Capacitor	ATC100B1R5BT500XT	ATC
R1, R2, R3, R4	4.7 kΩ Chip Resistors	CRCW12064K70FKEA	Vishay
PCB	0.020″, ε_r = 3.5	RF35A2	Taconic

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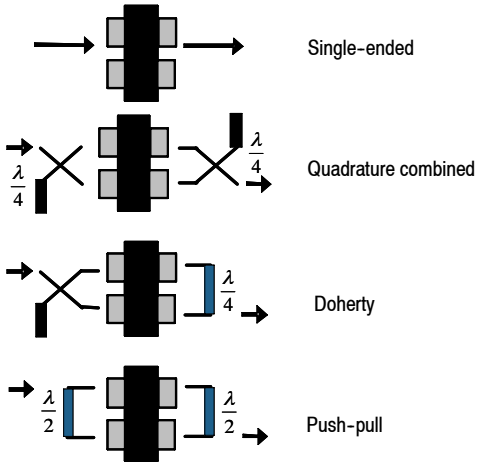

Figure 4. Possible Circuit Topologies

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TYPICAL CHARACTERISTICS

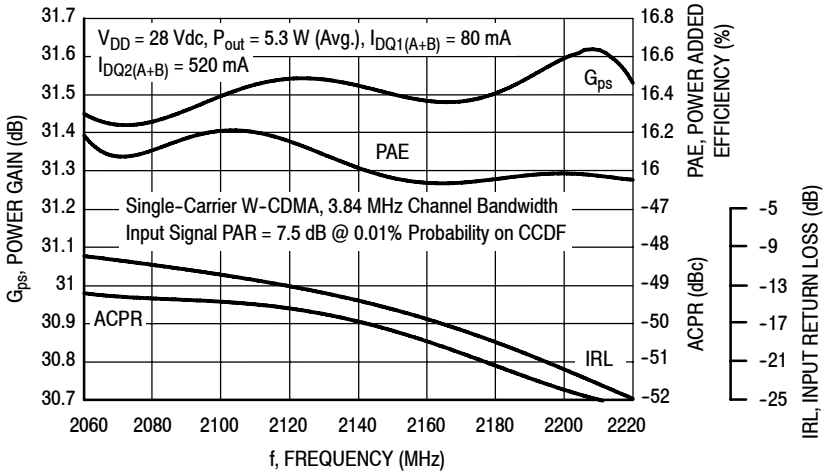

Figure 5. Power Gain, Power Added Efficiency, IRL and ACPR Broadband Performance @ P_{out} = 5.3 Watts Avg.

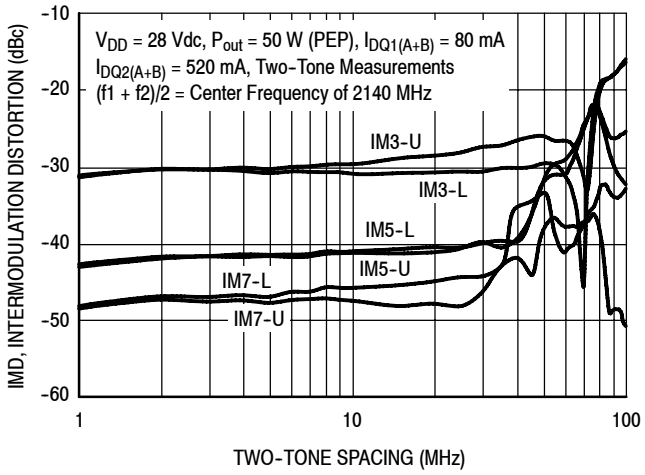

Figure 6. Intermodulation Distortion Products versus Two-Tone Spacing

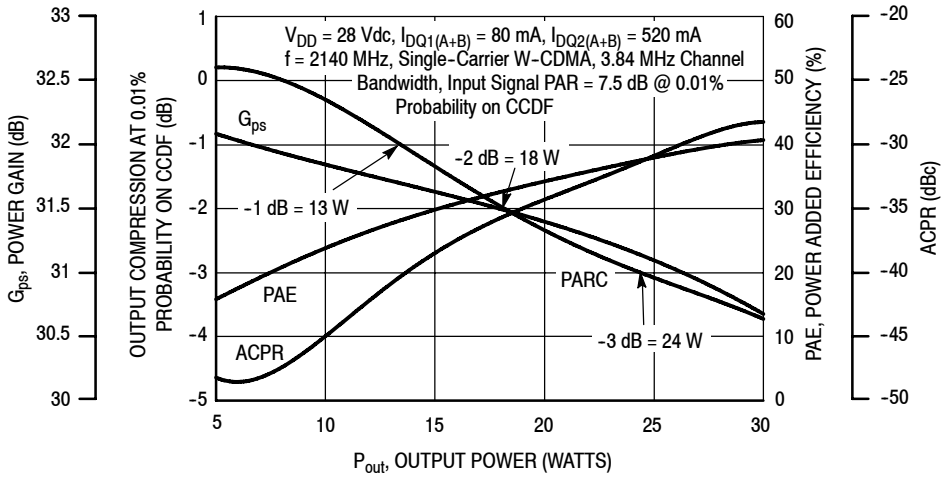

Figure 7. Output Peak-to-Average Ratio Compression (PARC) versus Output Power

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TYPICAL CHARACTERISTICS

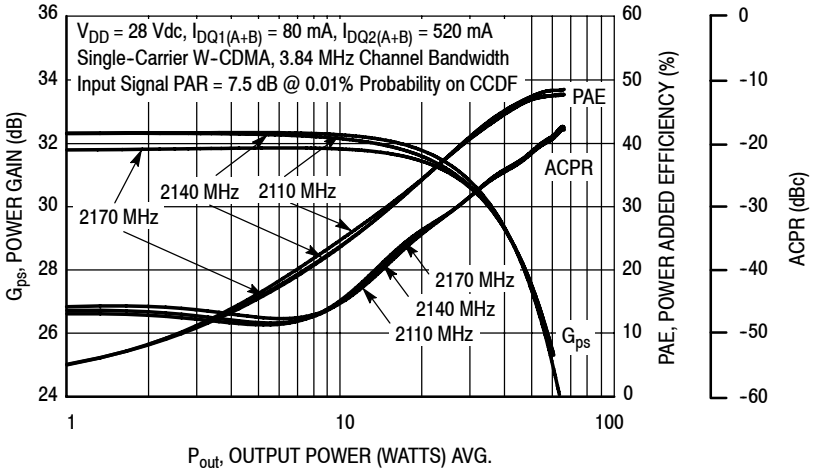

Figure 8. Single-Carrier W-CDMA Power Gain, Power Added Efficiency and ACPR versus Output Power

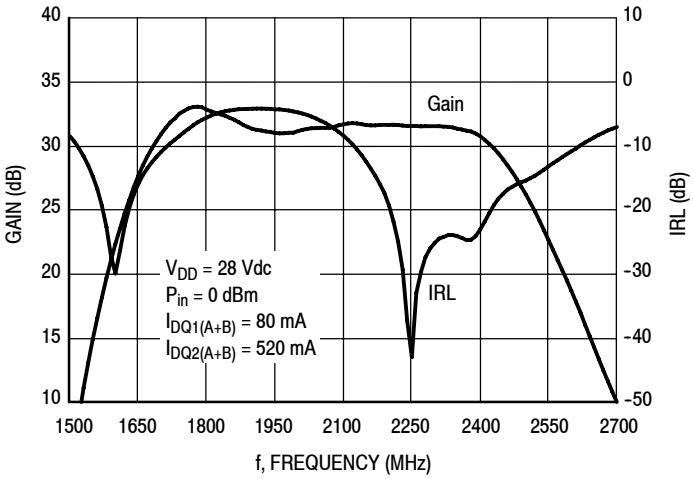

Figure 9. Broadband Frequency Response

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W-CDMA TEST SIGNAL

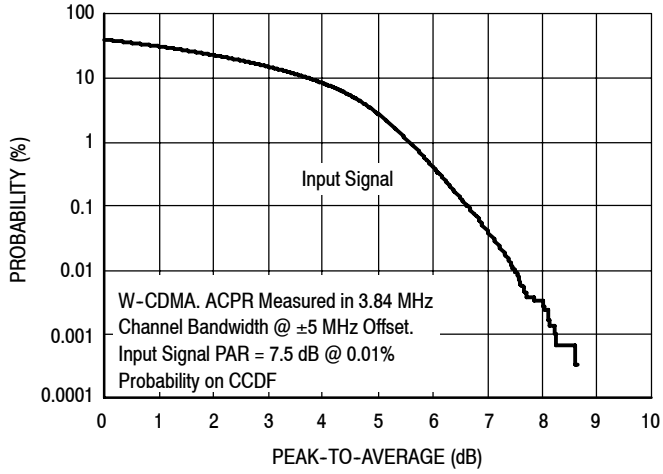

Figure 10. CCDF W-CDMA IQ Magnitude Clipping, Single-Carrier Test Signal

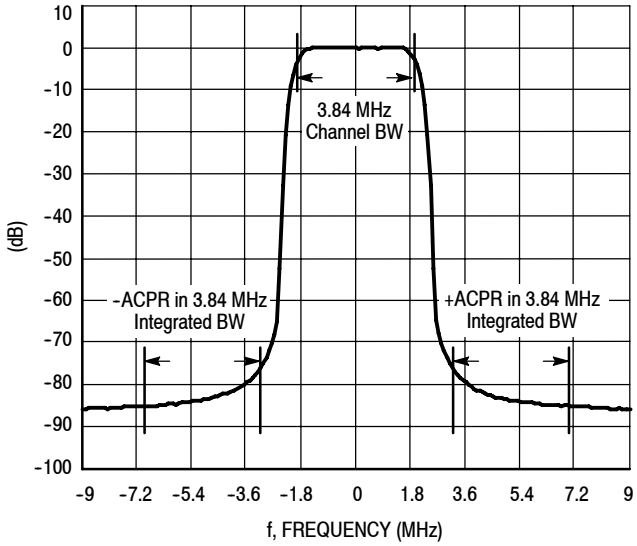

Figure 11. Single-Carrier W-CDMA Spectrum

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V_{DD} = 28 Vdc, $I_{DQ1(A+B)}$ = 80 mA, $I_{DQ2(A+B)}$ = 520 mA, P_{out} = 5.3 W Avg.

f MHz	Z_{source} Ω	Z_{load} Ω
2060	17.0 + j4.49	5.12 – j3.98
2080	17.2 + j4.94	5.07 – j4.10
2100	17.4 + j5.41	5.00 – j4.23
2120	17.7 + j5.88	4.90 – j4.36
2140	17.9 + j6.36	4.76 – j4.88
2160	18.2 + j6.84	4.59 – j4.60
2180	18.4 + j7.33	4.38 – j4.69
2200	18.7 + j7.84	4.15 – j4.77
2220	19.0 + j8.35	3.91 – j4.82

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

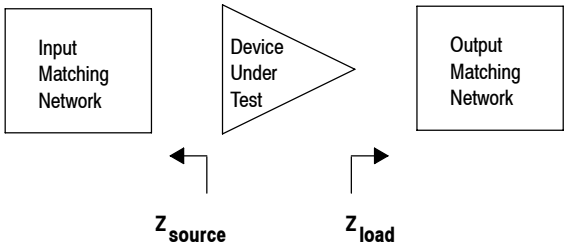

Figure 12. Series Equivalent Source and Load Impedance

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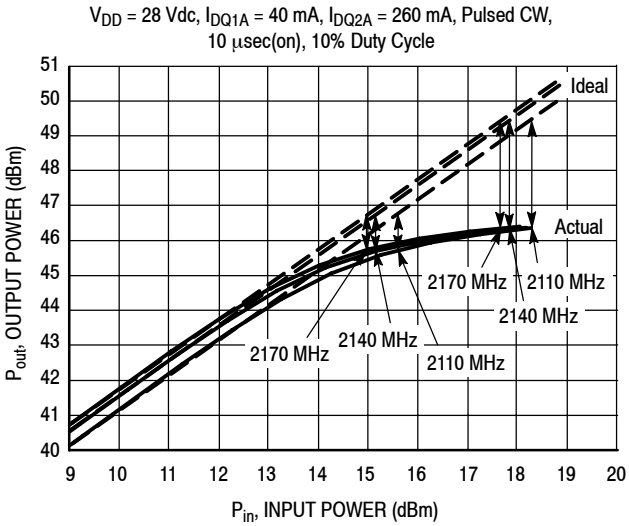
ALTERNATIVE PEAK TUNE LOAD PULL CHARACTERISTICS



NOTE: Load Pull Test Fixture Tuned for Peak P1dB Output Power @ 28 V

f (MHz)	P1dB		P3dB	
	Watts	dBm	Watts	dBm
2110	38	45.8	44	46.4
2140	37	45.7	44	46.4
2170	37	45.7	44	46.4

Test Impedances per Compression Level

f (MHz)		Z_{source} Ω	Z_{load} Ω
2110	P1dB	65.6 + j43.6	7.09 – j14.1
2140	P1dB	58.7 + j39.7	6.88 – j14.0
2170	P1dB	52.4 + j32.5	6.99 – j14.5

Figure 13. Pulsed CW Output Power versus Input Power @ 28 V

Note: Measurement made on a single path of the device under Class AB conditions.

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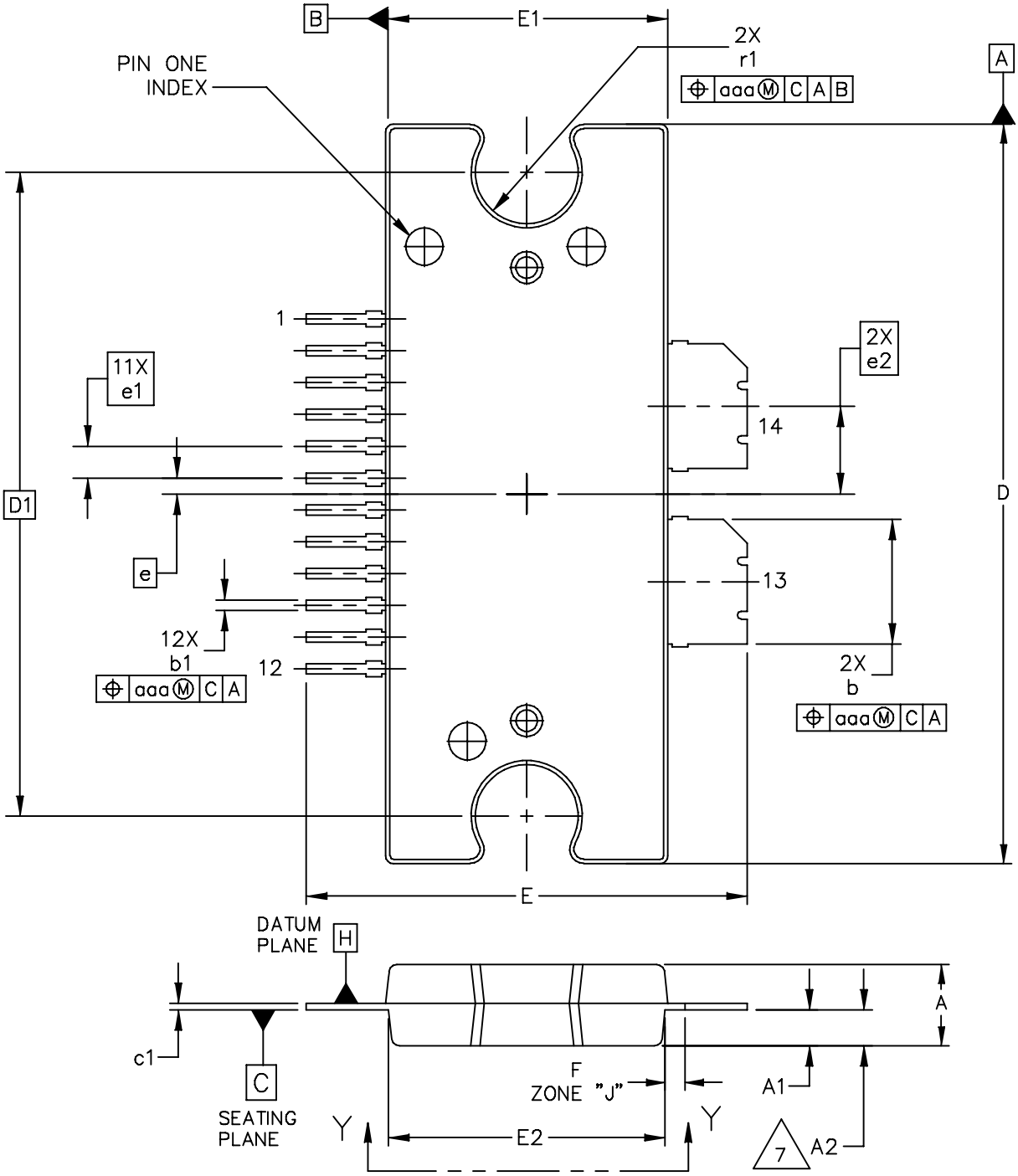
PACKAGE DIMENSIONS



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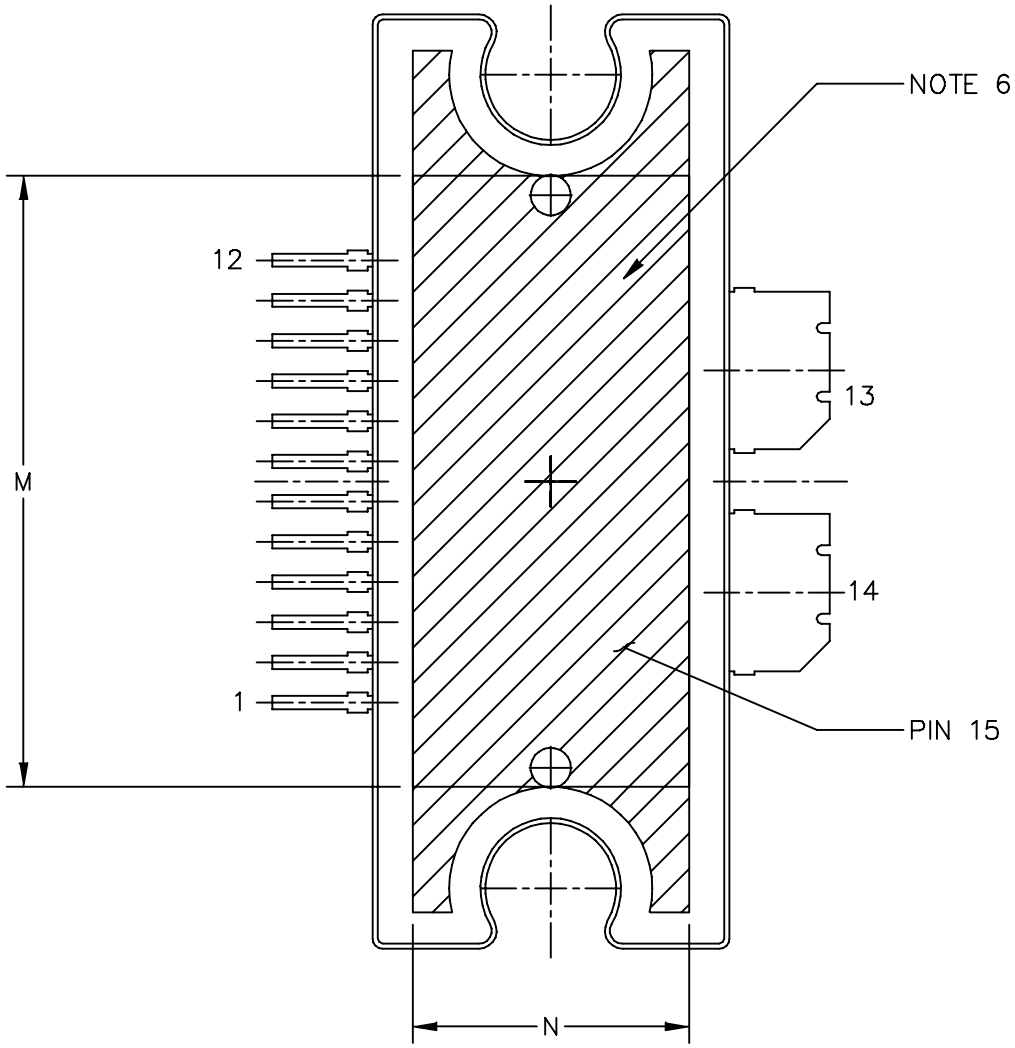

VIEW Y–Y

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NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.

4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 (0.15) PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.

5. DIMENSIONS "b" AND "b1" DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 (0.13) TOTAL IN EXCESS OF THE "b" AND "b1" DIMENSIONS AT MAXIMUM MATERIAL CONDITION.

6. HATCHING REPRESENTS THE EXPOSED AREA OFTHE HEAT SLUG.

7. DIM A2 APPLIES WITHIN ZONE "J" ONLY.

	INCH		MILLIMETER			INCH		MILLIMETER	
DIM	MIN	MAX	MIN	MAX	DIM	MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	b	.154	.160	3.91	4.06
A1	.039	.043	0.99	1.09	b1	.010	.016	0.25	0.41
A2	.040	.042	1.02	1.07	c1	.007	.011	0.18	0.28
D	.928	.932	23.57	23.67	e	.020 BSC		0.51 BSC	
D1	.810 BSC		20.57 BSC		e1	.040 BSC		1.02 BSC	
E	.551	.559	14.00	14.20	e2	.1105 BSC		2.807 BSC	
E1	.353	.357	8.97	9.07	r1	.063	.068	1.6	1.73
E2	.346	.350	8.79	8.89					
F	.025 BSC		0.64 BSC		aaa	.004		0.10	
M	.600	----	15.24	----					
N	.270	----	6.86	----					

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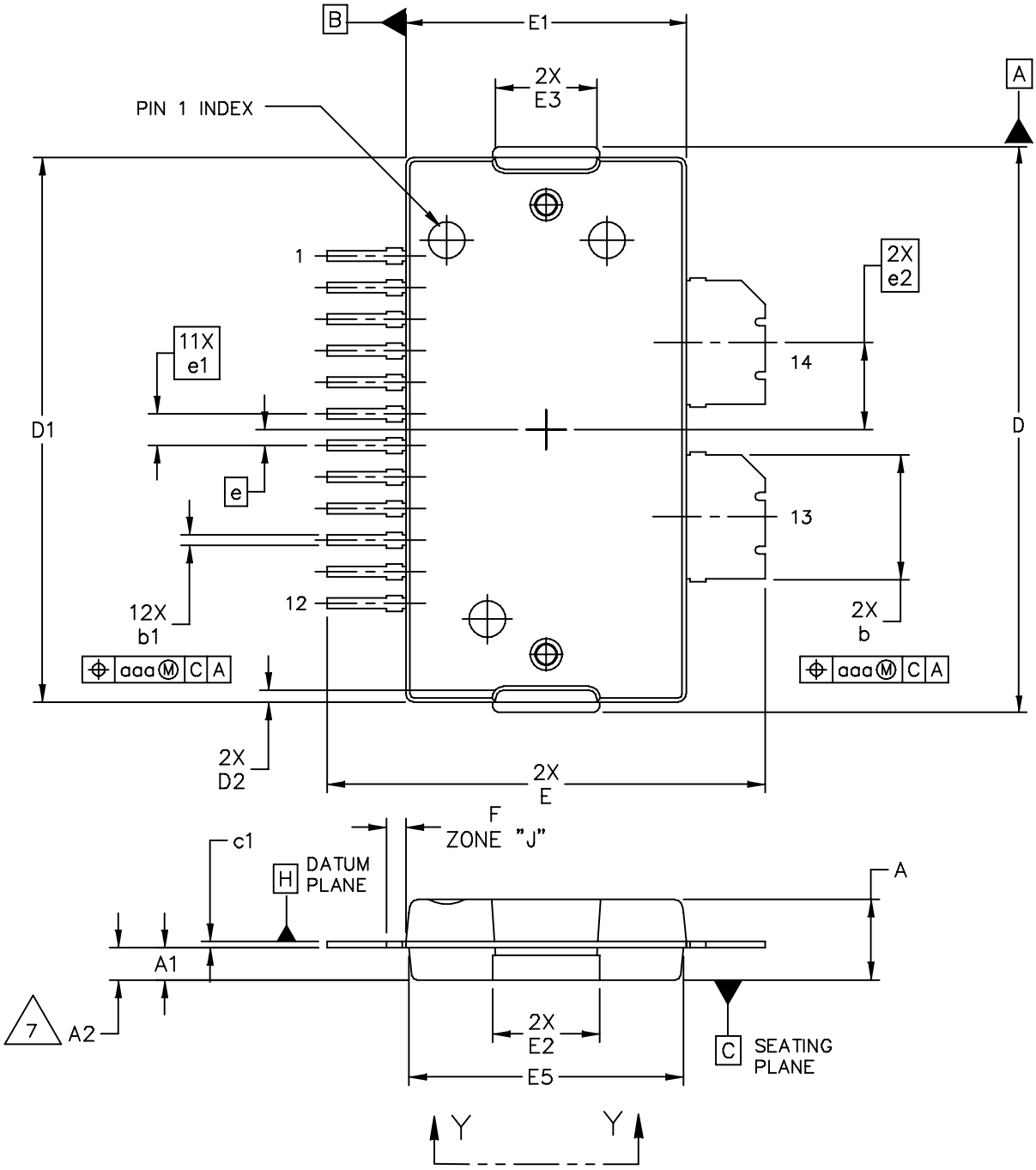

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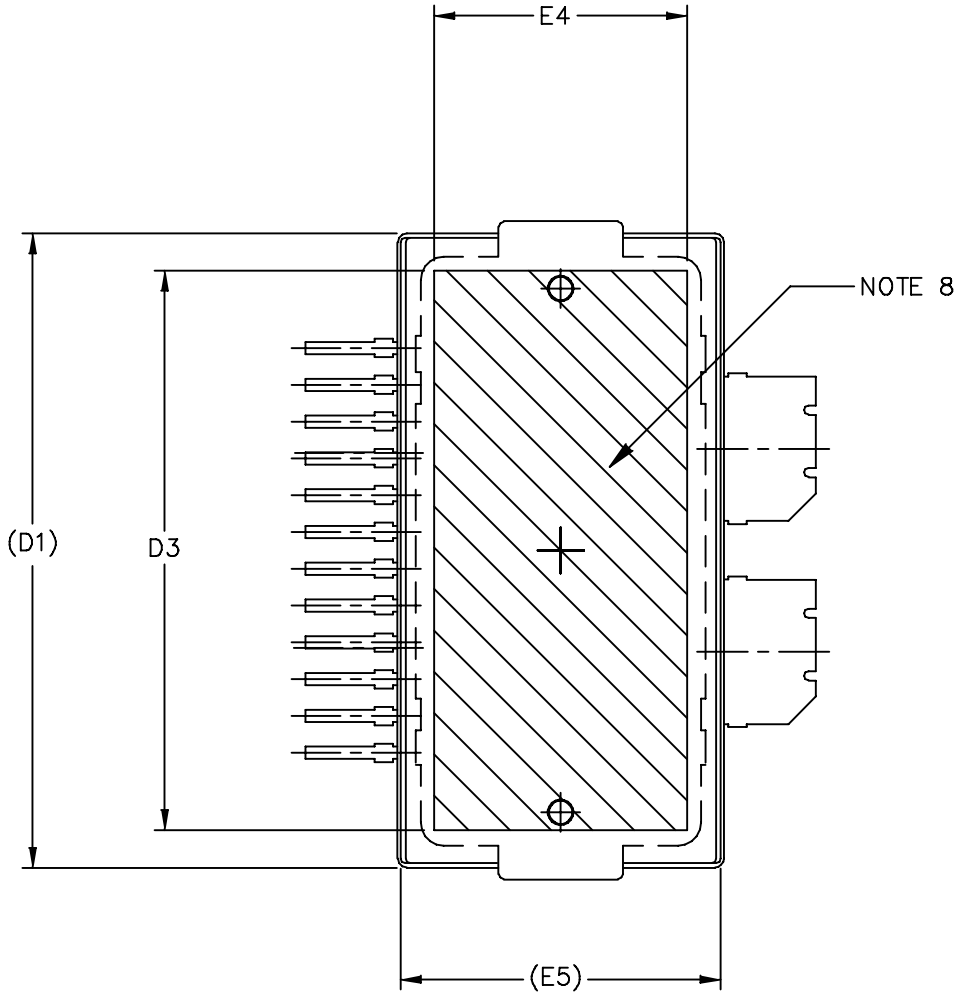

VIEW Y–Y

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TITLE: TO–270 WIDE BODY 14 LEAD	DOCUMENT NO: 98ASA10650D	REV: A
	CASE NUMBER: 1618–02	19 JUN 2007
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NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.

3. DATUM PLANE –H– IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.

4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE –H–.

5. DIMENSIONS "b" AND "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b" AND "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.

6. DATUMS –A– AND –B– TO BE DETERMINED AT DATUM PLANE –H–.

7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.

8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.

DIM	INCH MIN	INCH MAX	MILLIMETER MIN	MILLIMETER MAX	DIM	INCH MIN	INCH MAX	MILLIMETER MIN	MILLIMETER MAX
A	.100	.104	2.54	2.64	F	.025 BSC		0.64 BSC	
A1	.039	.043	0.99	1.09	b	.154	.160	3.91	4.06
A2	.040	.042	1.02	1.07	b1	.010	.016	0.25	0.41
D	.712	.720	18.08	18.29	c1	.007	.011	.18	.28
D1	.688	.692	17.48	17.58	e	.020 BSC		0.51 BSC	
D2	.011	.019	0.28	0.48	e1	.040 BSC		1.02 BSC	
D3	.600	---	15.24	---	e2	.1105 BSC		2.807 BSC	
E	.551	.559	14	14.2					
E1	.353	.357	8.97	9.07	aaa	.004		.10	
E2	.132	.140	3.35	3.56					
E3	.124	.132	3.15	3.35					
E4	.270	---	6.86	---					
E5	.346	.350	8.79	8.89					

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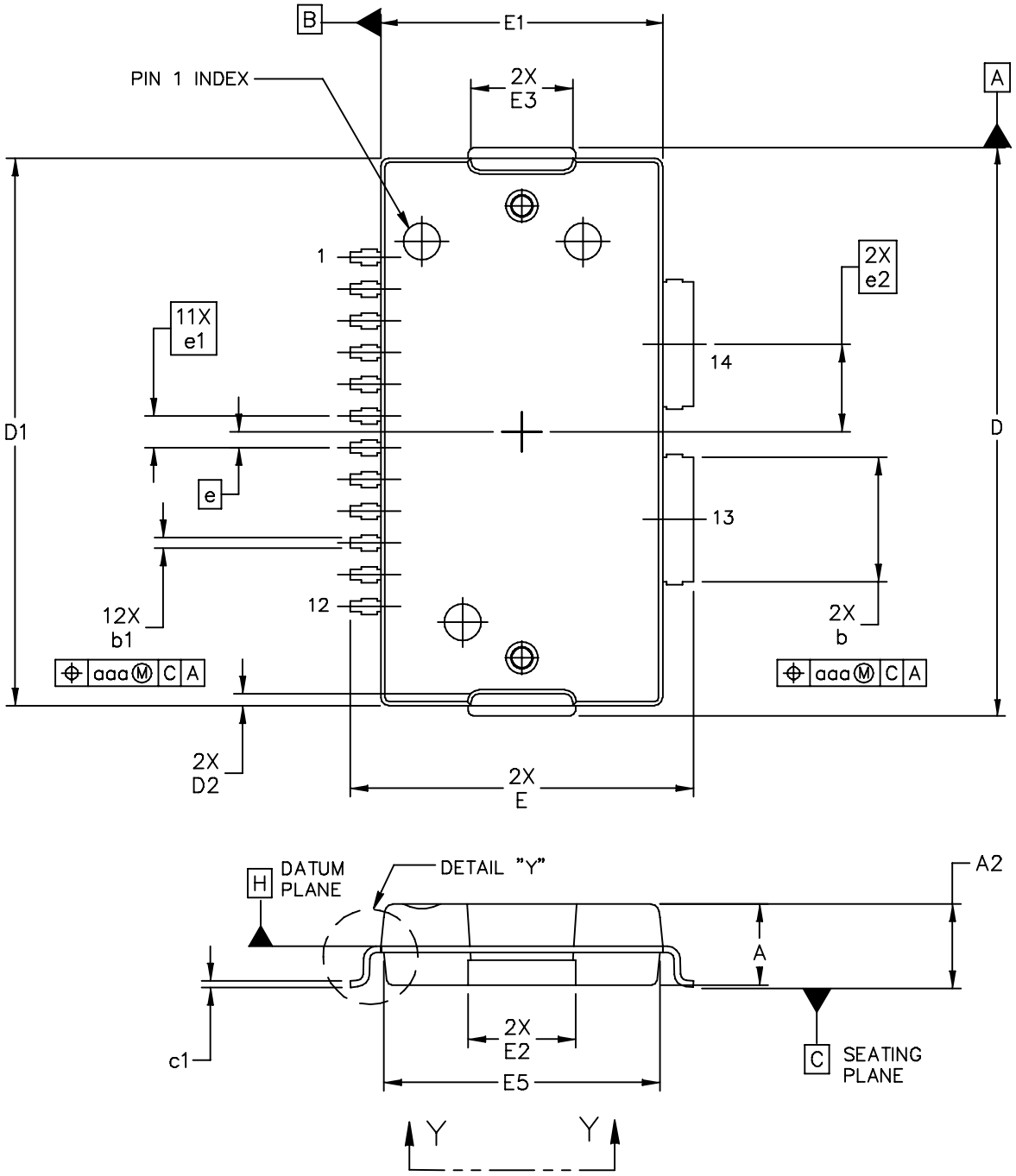

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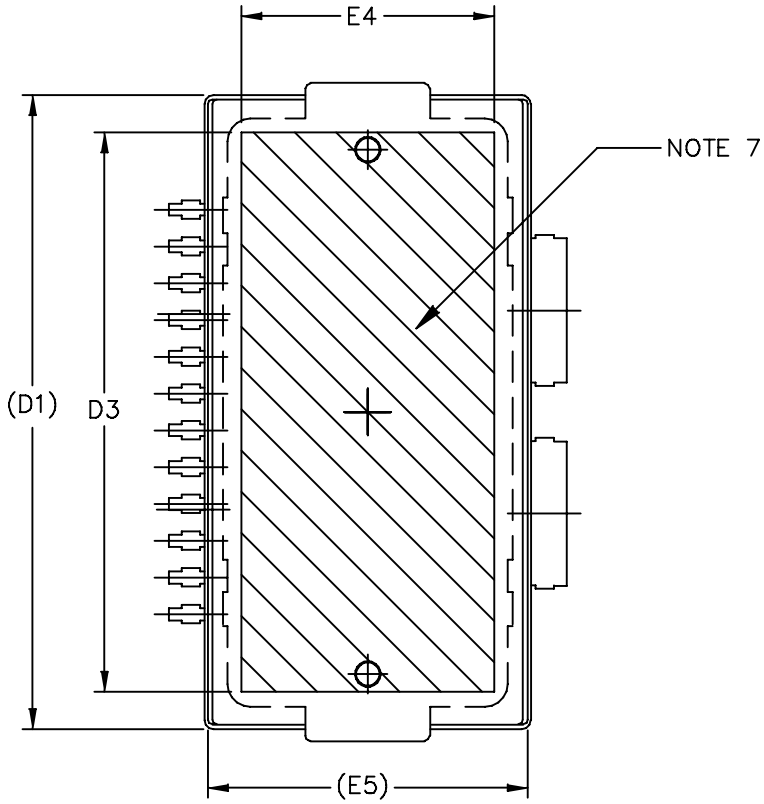
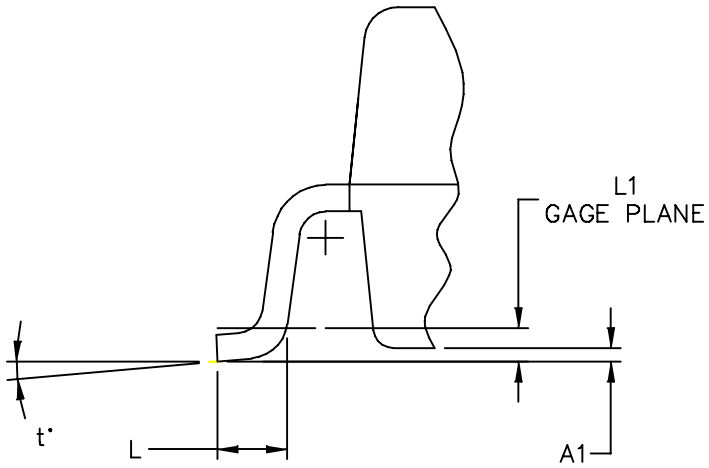


VIEW Y–Y



DETAIL "Y"

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NOTES:

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7. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.

DIM	INCH MIN	INCH MAX	MILLIMETER MIN	MILLIMETER MAX	DIM	INCH MIN	INCH MAX	MILLIMETER MIN	MILLIMETER MAX
A	.100	.104	2.54	2.64	L	.018	.024	0.46	0.61
A1	.001	.004	0.02	0.10	L1	.010 BSC		0.25 BSC	
A2	.099	.110	2.51	2.79	b	.154	.160	3.91	4.06
D	.712	.720	18.08	18.29	b1	.010	.016	0.25	0.41
D1	.688	.692	17.48	17.58	c1	.007	.011	.18	.28
D2	.011	.019	0.28	0.48	e	.020 BSC		0.51 BSC	
D3	.600	---	15.24	---	e1	.040 BSC		1.02 BSC	
E	.429	.437	10.9	11.1	e2	.1105 BSC		2.807 BSC	
E1	.353	.357	8.97	9.07	t	2°	8°	2°	8°
E2	.132	.140	3.35	3.56					
E3	.124	.132	3.15	3.35	aaa	.004		.10	
E4	.270	---	6.86	---					
E5	.346	.350	8.79	8.89					

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TITLE: TO–270 WIDE BODY
14 LEAD
GULL WING

DOCUMENT NO: 98ASA10653D | REV: A

CASE NUMBER: 1621–02 | 19 JUN 2007

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PRODUCT DOCUMENTATION, TOOLS AND SOFTWARE

Refer to the following documents, tools and software to aid your design process.

Application Notes

- AN1907: Solder Reflow Attach Method for High Power RF Devices in Plastic Packages
- AN1955: Thermal Measurement Methodology of RF Power Amplifiers
- AN1977: Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family
- AN3263: Bolt Down Mounting Method for High Power RF Transistors and RFICs in Over-Molded Plastic Packages
- AN3789: Clamping of High Power RF Transistors and RFICs in Over-Molded Plastic Packages

Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

Software

- Electromigration MTTF Calculator
- RF High Power Model
- .s2p File

For Software and Tools, do a Part Number search at http://www.freescale.com, and select the “Part Number” link. Go to the Software & Tools tab on the part’s Product Summary page to download the respective tool.

REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	Dec. 2010	• Initial Release of Data Sheet

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